

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|------------------|
| 1 | 2139 | dmd or (digital adj micro adj mirror adj device) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 15:25 |
| 3 | 1590 | (dmd or (digital adj micro adj mirror adj device)) and (method or process or manufacture) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 15:36 |
| 4 | 37 | (dmd or (digital adj micro adj mirror adj device)) and wafer and (chip same mirror) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 15:37 |
| 2 | 69 | (dmd or (digital adj micro adj mirror adj device)) and (metal\$ with (wafer or chip)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 16:59 |
| 5 | 8330 | mirror with (wafer or chip) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:00 |
| 6 | 1507 | (mirror with (wafer or chip)) and &pd>20001005 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:02 |
| 7 | 300 | (mirror with (wafer or chip)) and (pad with chip) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:03 |
| 8 | 434 | (dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:05 |
| 9 | 46 | ((dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break)) and photoresist | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:05 |
| 10 | 6 | ((dmd or (digital adj micro adj mirror adj device)) and (diec or singulate or cut or break)) and (remove with photoresist) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB | 2002/03/27 17:05 |